2SB1148, 2SB1148A

Silicon PNP epitaxial planar type

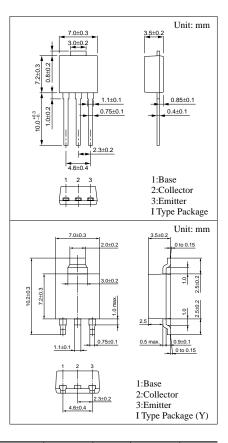
For low-voltage switching Complementary to 2SD1752 and 2SD1752A

Features

- ullet Low collector to emitter saturation voltage $V_{CE(sat)}$
- High-speed switching
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

Absolute Maximum Ratings $(T_C=25^{\circ}C)$

Parameter		Symbol	Ratings	Unit	
Collector to	2SB1148	37	-40	V	
base voltage	2SB1148A	V_{CBO}	-50		
Collector to	2SB1148	**	-20	V	
emitter voltage	2SB1148A	V_{CEO}	-40		
Emitter to base voltage		V_{EBO}	-7	V	
Peak collector current		I_{CP}	-20	A	
Collector current		I_C	-10	A	
Collector power	T _C =25°C	D	15	337	
dissipation	Ta=25°C	P_{C}	1.3	W	
Junction temperature		T_{j}	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



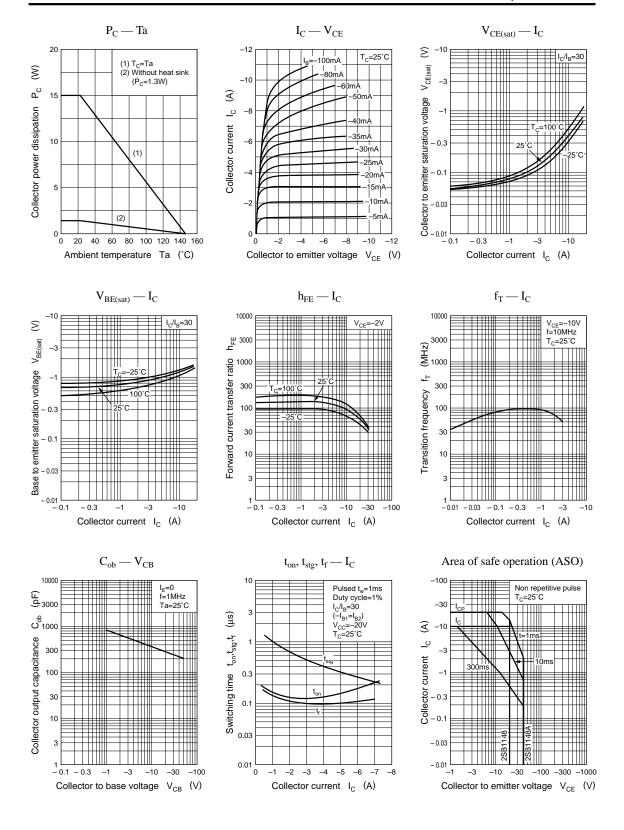
Electrical Characteristics (T_C=25°C)

Parameter		Symbol	Conditions	min	typ	max	Unit	
Collector cutoff	2SB1148	T	$V_{CB} = -40V, I_{E} = 0$			-50	μА	
current	2SB1148A	I _{CBO}	$V_{CB} = -50V, I_{E} = 0$			-50		
Emitter cutoff current		I_{EBO}	$V_{EB} = -5V, I_C = 0$			-50	μА	
Collector to emitter	2SB1148	37	V_{CEO} $I_C = -10 \text{mA}, I_B = 0$	-20			V	
voltage	2SB1148A	V _{CEO}		-40				
Forward current transfer ratio		h _{FE1}	$V_{CE} = -2V, I_C = -0.1A$	45				
		h _{FE2} *	$V_{CE} = -2V, I_C = -3A$	90		260		
Collector to emitter saturation voltage		V _{CE(sat)}	$I_C = -10A, I_B = -0.33A$			- 0.6	V	
Base to emitter saturation voltage		V _{BE(sat)}	$I_C = -10A, I_B = -0.33A$			-1.5	V	
Transition frequency		f_T	$V_{CE} = -10V, I_{C} = -0.5A, f = 10MHz$		100		MHz	
Collector output capacitance		C _{ob}	$V_{CB} = -10V, I_E = 0, f = 1MHz$		400		pF	
Turn-on time		t _{on}	$I_C = -3A$, $I_{B1} = -0.1A$, $I_{B2} = 0.1A$, $V_{CC} = -20V$		0.1		μs	
Storage time		t _{stg}			0.5		μs	
Fall time		t _f			0.1		μs	

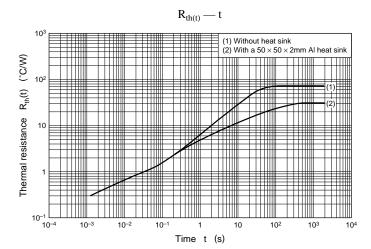
*h_{FE2} Rank classification

Rank	Q	P		
h _{FE2}	90 to 180	130 to 260		

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